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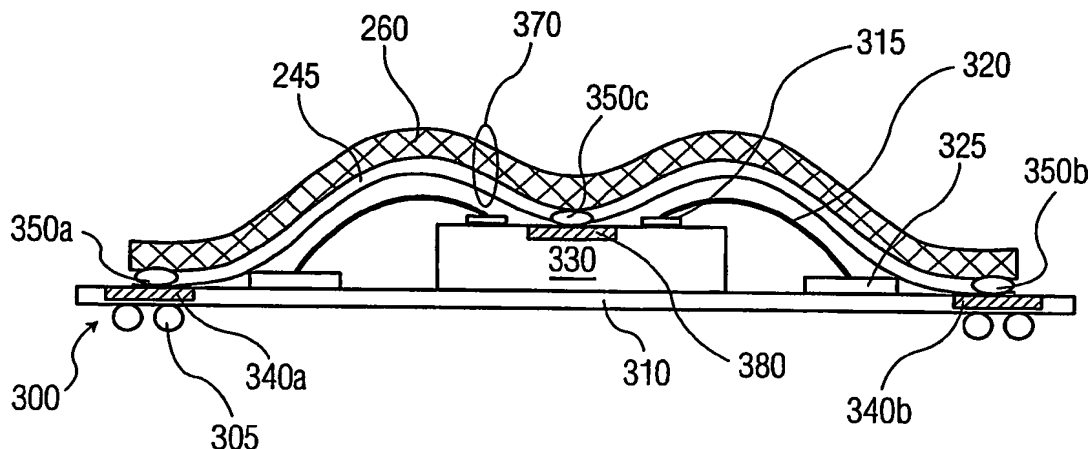
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[Continued on next page]

(54) Title: GROUND ARCH FOR WIREBOND BALL GRID ARRAYS



(57) Abstract: A structure provides for the control of bond wire impedance. In an example embodiment, there is an integrated circuit device (100) comprising an integrated circuit (130) having a plurality (115) of grounding pads, signal pads, and power pads and a package (110) for mounting the integrated circuit and includes a conductive path having at least one reference trace (140) that surrounds the integrated circuit. A grounding arch (170) formed by a dielectric-coated metal tape is disposed over the integrated circuit and connected to its ground pad in order to provide heat dissipation and EMI shielding.

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- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for all designations*

- with international search report
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments

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